



# Material Declaration Sheet

Vishay General Semiconductor - PDD

Date: 13/Aug/20

Part / Product Family Details							
Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mm-yyyy	Total product Weight (gm)	Resistance value	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemptions Used
1N3611GP-E3 to 1N3614GP-E3 1N4245GP-E3 to 1N4249GP-E3 1N4942GP-E3 to 1N4948GP-E3 1N3957GP-E3 BYW27-100GP-E3 BYM27-400GP-E3 BYM27-800GP-E3 GI250-1-E3 to GI250-4-E3 GP08A-E3 to GP08I-E3 GP10-4002-E3 to GP10-4007-E3 GP10A-E3 to GP10Y-E3 RGP10A-E3 to RGP10M-E3 GP02-40-E3 GP10J-051-E3 GP10M-700TE3 RGP10A-013E3 RGP10J-057E3 RGP10K-5008E3 EGP10G-E3 1N4001GPE-E3 to 1N4007GPE-E3 1N4942GPE-E3 to 1N4948GPE-E3 BA1590GPE-E3 GP08AF-E3 to GP08IE-E3 GP10-4002E-E3 to GP10-4007E-E3 EGP10AE-E3 to EGP10GE-E3 EGP10A-E3 to EGP10G-E3 1N4933GP-E3 to 1N4937GP-E3 BA1575GP-E3 to BA1596GP-E3 BA1596GP-E3 GP10AE-E3 to GP10FE-E3 RGP02-12E-E3 to RGP02-20E-E3 RGP10AE-E3 to RGP10ME-E3 EGP10G-E3	YES WITH EXEMPTION	01-12-2004	0.3	N/A	Yes	China	One

Technical Information: refer to <a href="http://www.vishay.com/techinfo/Passives">http://www.vishay.com/techinfo/Passives</a>							
Terminal Plating / Grid Array Material	Terminal Base Alloy	JESD-97 Pb-Free Material Code Marking	J-STD-20D MSL Rating	Reflow Peak Process Body Temperature	Reflow Maximum number of cycles	Reflow Max. Time at Peak Temperature (sec)	Soldering Compatibility (SnPb/Pb-Free)

Material Composition								
Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance (gm)	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
					%	ppm		
Chip	Electronics (e.g. pc boards, displays)	Silicon and others (business secret)	-	0.00040	100.00	1000000	0.13	
Molybdenum Sling	Other special metals	Molybdenum (Mo)	7439-98-7	0.01740	100.00	1000000	5.80	
Glass Powder	Ceramics / glass	Biboron-trioxide	1303-86-2	0.00264	30.00	300000	0.88	
		Silicon dioxide	7631-86-9	0.00070	8.00	80000	0.23	
		Zinc oxide	1314-13-2	0.00528	60.00	600000	1.76	
		Lead-monoxide	1317-36-8	0.00018	2.00	20000	0.06	Exemption No:7(c)-1
Lead Wire	Conner (e.g. conner amounts in cable harnesses)	Copper	7440-50-8	0.23030	100.00	1000000	76.77	
Solder 80	Other special metals	Silver	7440-22-4	0.00015	15.00	150000	0.65	
		Copper	7440-50-8	0.00080	80.00	800000	0.27	
		Phosphorus	7723-14-0	0.00005	5.00	50000	0.02	
Encapsulation	Other duromers	Silicon dioxide (SiO2)	14808-60-7	0.02943	80.20	802000	9.81	
		Epoxy Resin	29690-82-2	0.00472	12.85	128500	1.57	
		Phenolic Resin	9003-35-4	0.00182	4.95	49500	0.61	
		Antimony trioxide (Sb2O3)	1309-64-4	0.00037	1.00	10000	0.12	
		Brominated Epoxy	68928-70-1	0.00037	1.00	10000	0.12	
Surface finish	Other special metals	Tin	7440-31-5	0.00540	100.00	1000000	1.80	
Marking	Other special metals	Synthetic resin	53192-18-0	0.00003	65.00	650000	0.01	
		Starting agent	21245-01-2	0.00001	10.00	100000	0.00	
		Dye	7429-90-5	0.00001	15.00	150000	0.00	
		Additive	947-19-3	0.00000	5.00	50000	0.00	
		Silicon dioxide	112945-52-5	0.00000	5.00	50000	0.00	

**EU-RoHS Directive-2011/66/EU** MCV of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and MCV of 0.01% by mass cadmium

This MSD valid for List of PN's

**Exemption Used** 7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

**Note :-** (i) All information is based on data received from our vendors & subjected to change without prior notice.  
(ii) Substance weight are derived from MSDS.

Vishay General Semiconductor - PDD  
233, Pao Chiao Rd., Hsin Tien, Taipei, Taiwan, R.O.C. 23145  
ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENTS

Build Vishay into your Design

One of the World's Largest Manufacturers of Discrete Semiconductors and Passive Components